

# **A physics-based model for Charge- Trapping memory simulation**

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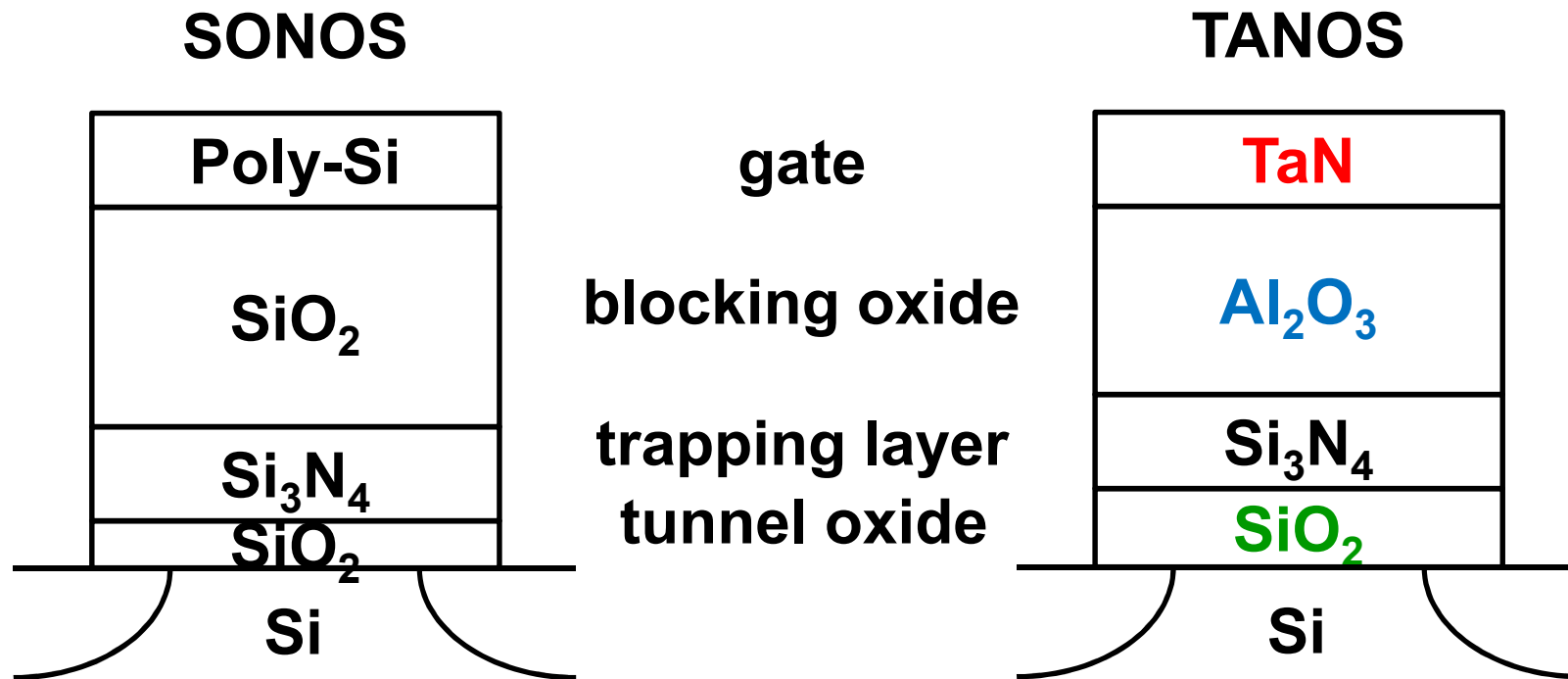
# Purpose

- **Charge-trapping devices like TANOS are a promising candidates to replace Floating Gate memories**
- **Understanding the physical mechanisms governing device operation is fundamental for performance and reliability optimization**
- **This requires accurate simulation models**
- **We present results obtained with a physical model accounting for both charge trapping in alumina and temperature effects**

# Outline

- **Introduction**
- **Physical Model**
- **Model Results**
  - **Program and Erase operations**
  - **Charge Separation Experiments**
  - **Charge Trapping into Alumina**
  - **Effects of Temperature**
- **Toward a SPICE-like model of the TANOS cell**
- **Conclusions**

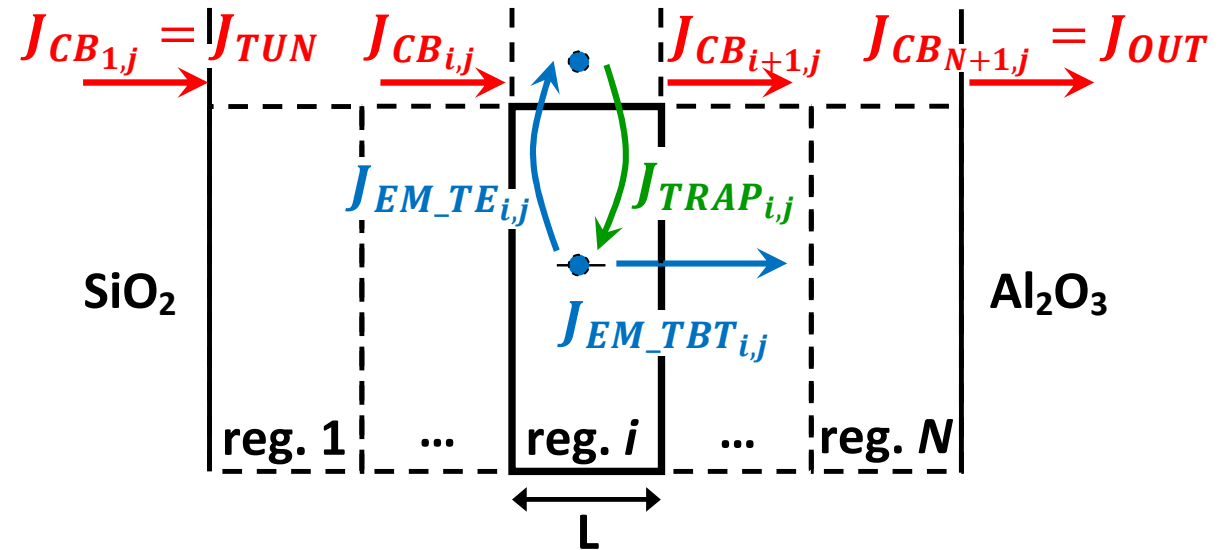
# Introduction



- Better retention (**thicker** tunnel SiO<sub>2</sub>)
- Improved program/erase speed (**high-k**)
- Improved erase V<sub>T</sub> saturation level (**metal gate**)

# Physical Model

- Charge trapping and transport across the stack is described by a set of differential equations solved by discretizing space and time (indexes  $i$  and  $j$ )

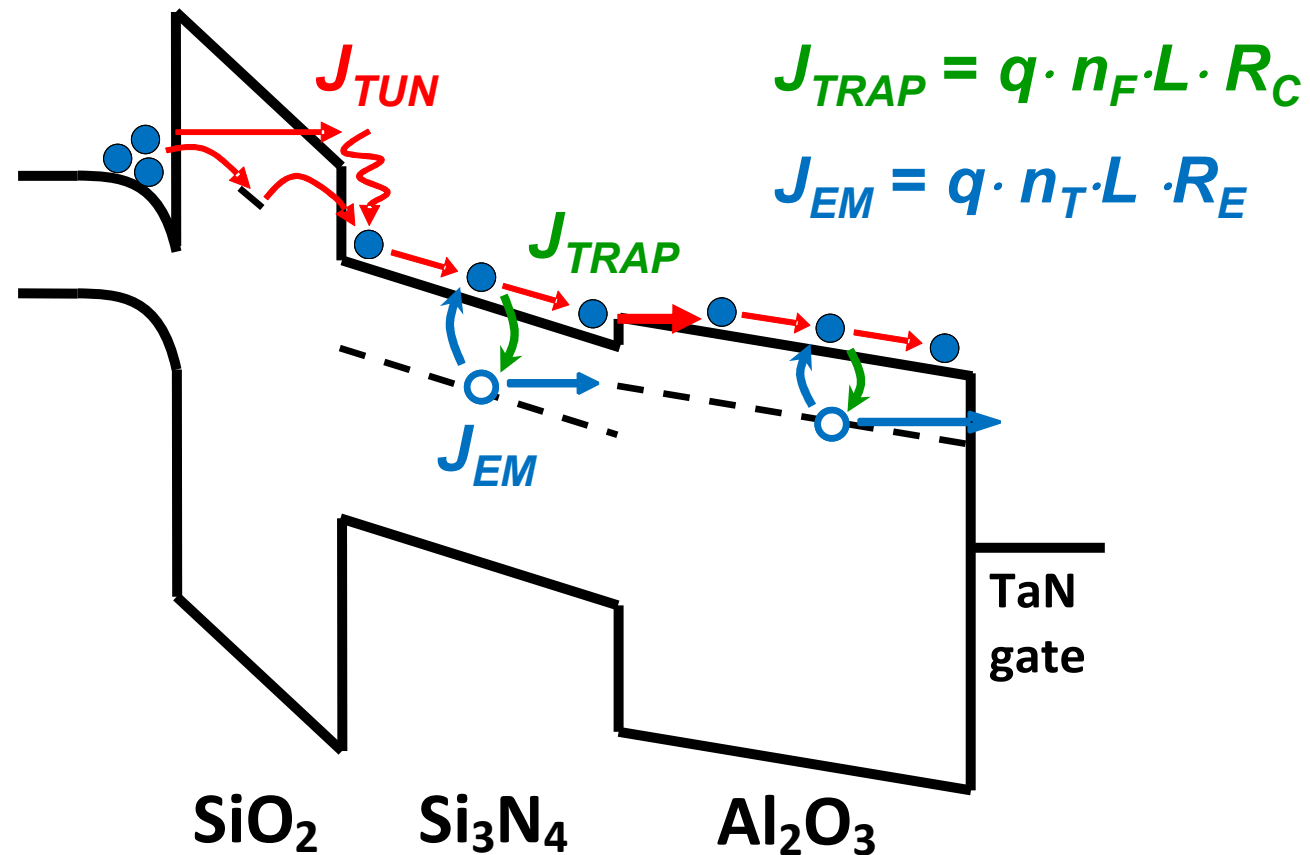


$$J_{CB_{i,j}} = q\mu \left[ n_{F_{i,j}} F_{i,j-1} + \frac{k_B T}{q} \frac{n_{F_{i,j}} - n_{F_{i+1,j}}}{L} \right]$$

$$\frac{qL(n_{F_{i,j}} - n_{F_{i,j-1}})}{t_j - t_{j-1}} = J_{CB_{i,j}} - J_{CB_{i+1,j}} + J_{EM_{i,j}} - J_{TRAP_{i,j}}$$

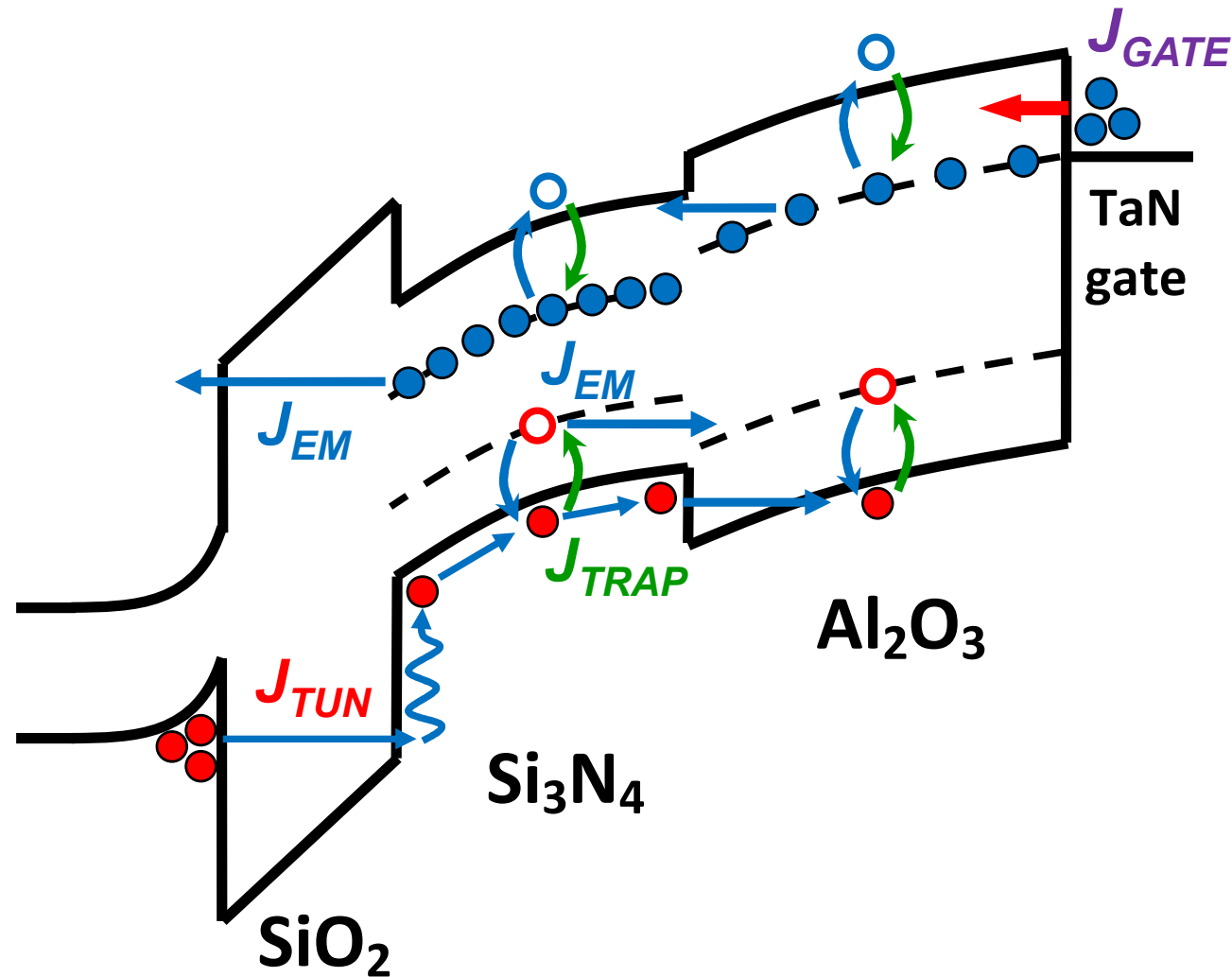
$$\frac{qL(n_{T_{i,j}} - n_{T_{i,j-1}})}{t_j - t_{j-1}} = J_{TRAP_{i,j}} - J_{EM_{i,j}}$$

# Physical Mechanisms: Program



- $J_{TUN}$  includes tunneling and TAT contributions
- $J_{TRAP}$  is calculated using Shockley-Read-Hall theory
- $J_{EM}$  includes thermal and trap-to-band tunneling emission

# Physical Mechanisms: Erase



- $J_{TUN}$  is the hole current injected from the substrate
- $J_{GATE}$  is the electron current injected from the gate

# Solution Algorithm

- **Iterative methods commonly used to solve the equation system**
- **We developed a novel algorithm allowing deriving a closed form solution of the above system**

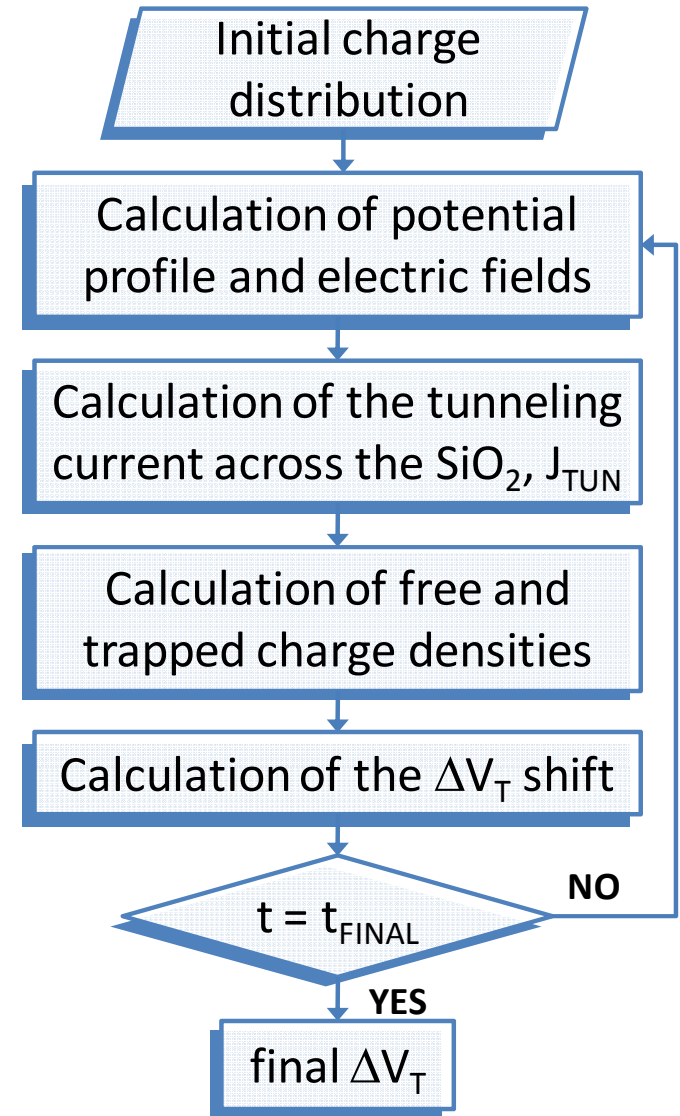
$$n_{Fi,j} = (\beta_{i,j} J_{CBi,j} - \gamma_{i,j}) / \alpha_{i,j}$$

$$\alpha_{i,j} = \begin{cases} \alpha_{i+1,j} A_{i,j} + \beta_{i+1,j} C_{i,j} & i < N \\ qL \mu F_{i,j-1} P_{OUT} + C_{i,j} & i = N \end{cases}$$

$$\beta_{i,j} = \begin{cases} \beta_{i+1,j} + \alpha_{i+1,j} B & i < N \\ 1 & i = N \end{cases}$$

$$\gamma_{i,j} = \begin{cases} \gamma_{i+1,j} + \beta_{i+1,j} Y_{i,j} + \beta_{i+1,j} J_{TUN} & i = 1 \\ \gamma_{i+1,j} + \beta_{i+1,j} Y_{i,j} & 1 < i < N \\ Y_{i,j} & i = N \end{cases}$$

$$J_{CBi+1,j} = J_{CBi,j} - n_{Fi,j} C_{i,j} + Y_{i,j}$$





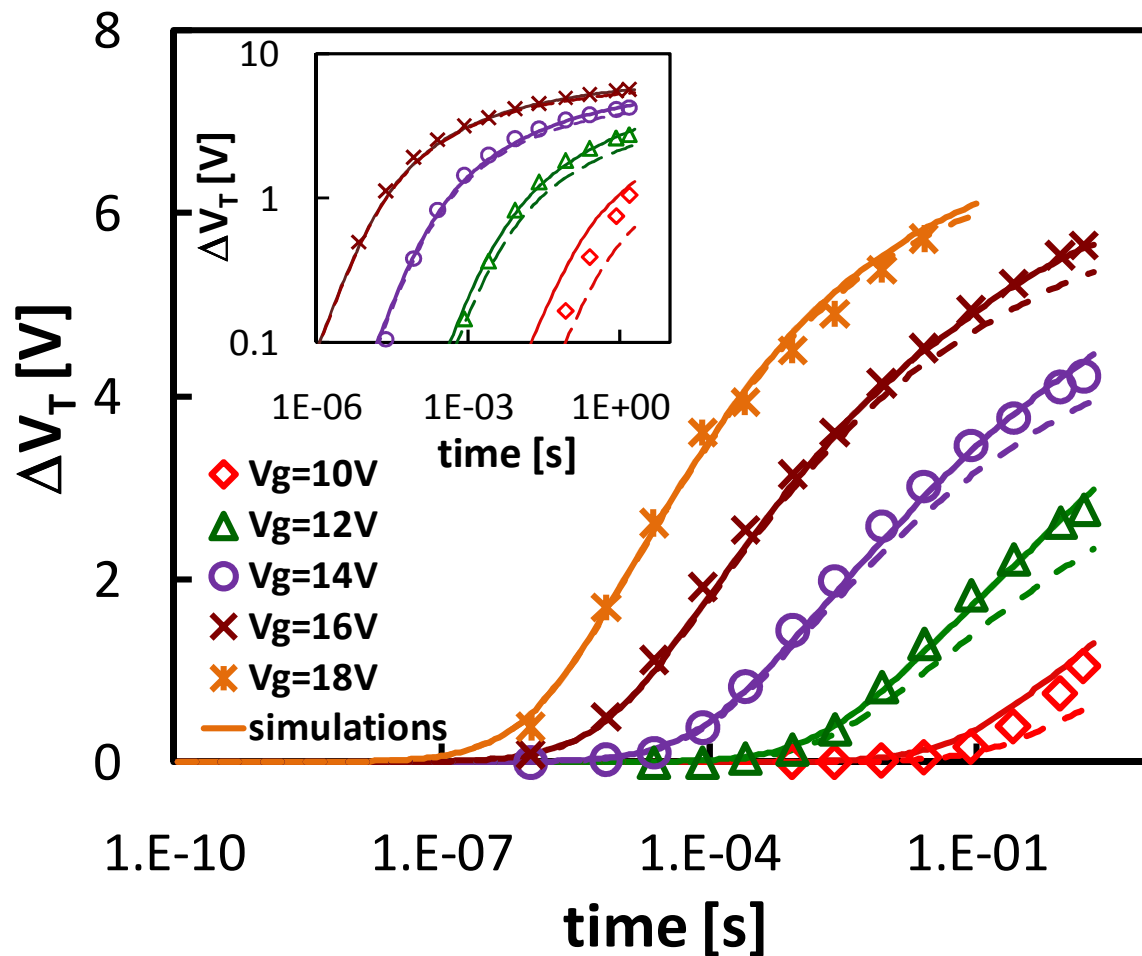
# Samples

- Model used to reproduce program, erase and retention of TANOS devices manufactured by different technologies (A, B, C)

	Sample	$t_{OX}$ [nm]	$t_{NI}$ [nm]	$t_{AL}$ [nm]	
TANOS	A1	3	5	11.5	
	A2	4	5	11.5	
	A3	4	8.7	11.5	highest $t_N/t_{AL}$ ratio
	A4	4.5	7	12	
	B1	4	6	12	
	B2	5	6	12	
	C1	4.5	6	15	
	C2	4.5	4	15	lowest $t_N/t_{AL}$ ratio
	C3	4.5	6	10	
	TAOS	C4	1	-	5
C5		1	-	10	
C6		1	-	15	

# Program

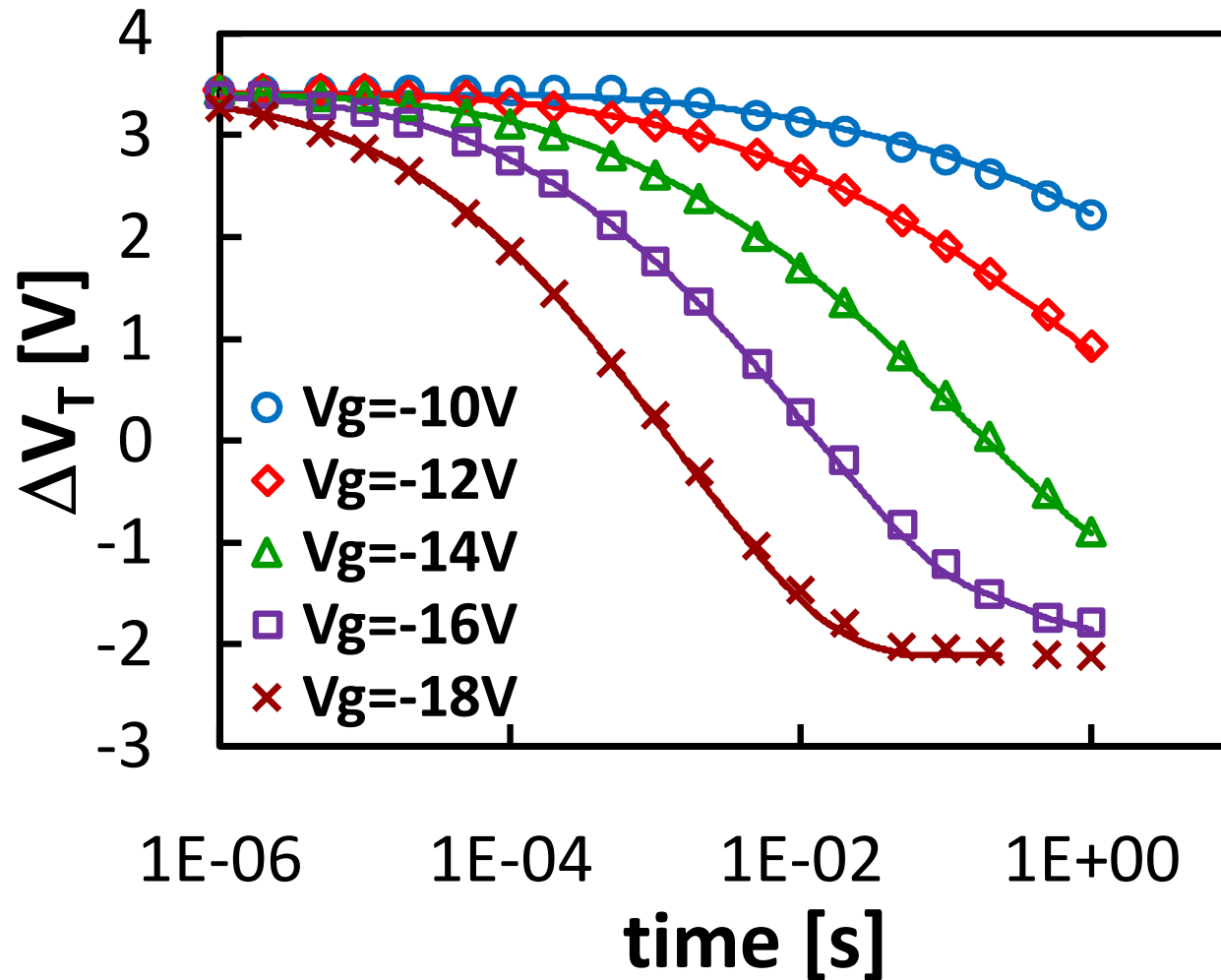
- TAT through  $\text{SiO}_2$  is fundamental to achieve high accuracy at low  $V_G$  and high times (low fields)



sample C1  
 $t_{\text{OX}}/t_{\text{N}}/t_{\text{AL}} = 4.5/6/15$

# Erase

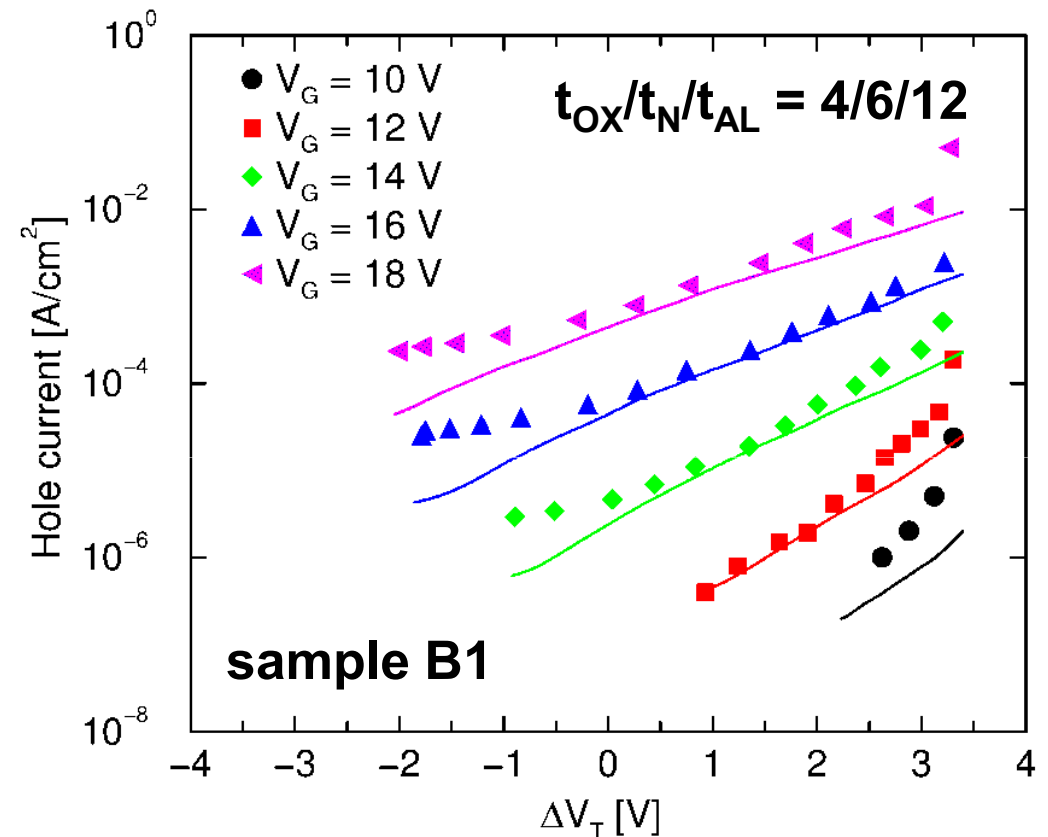
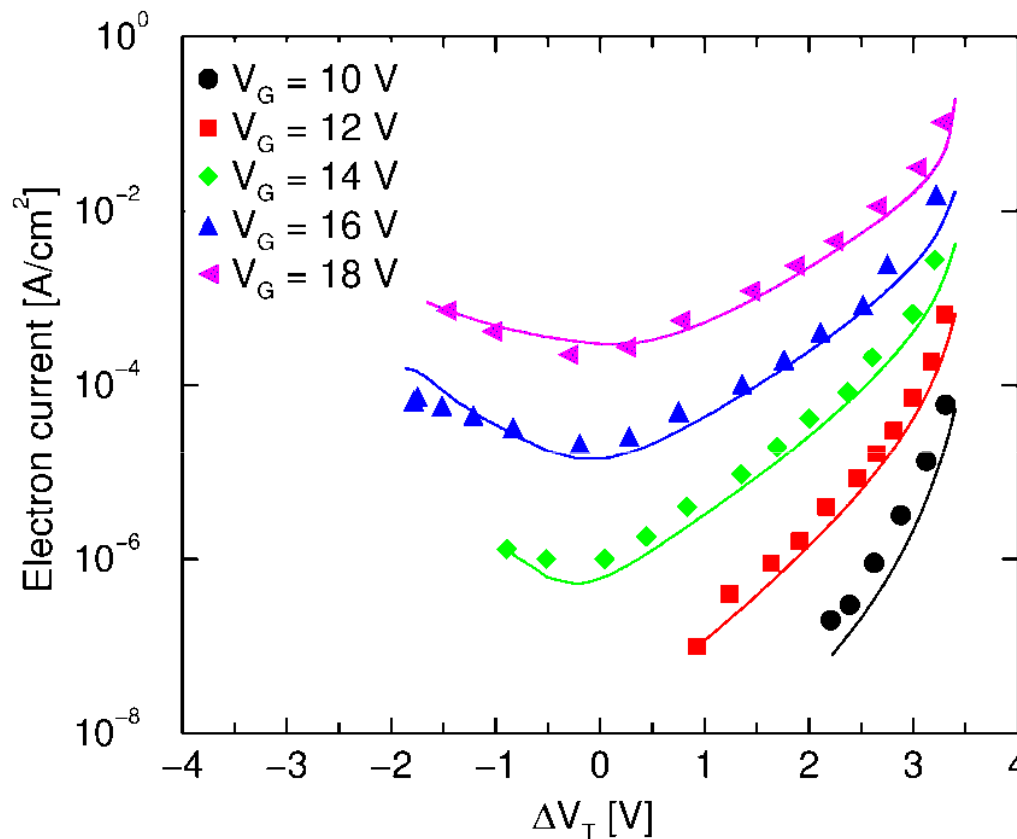
- Simulations accurately reproduce erase transients
- Holes significantly contribute to TANOS erase at high  $|V_G|$



sample B1  
 $t_{OX}/t_N/t_{AL} = 4/6/12$

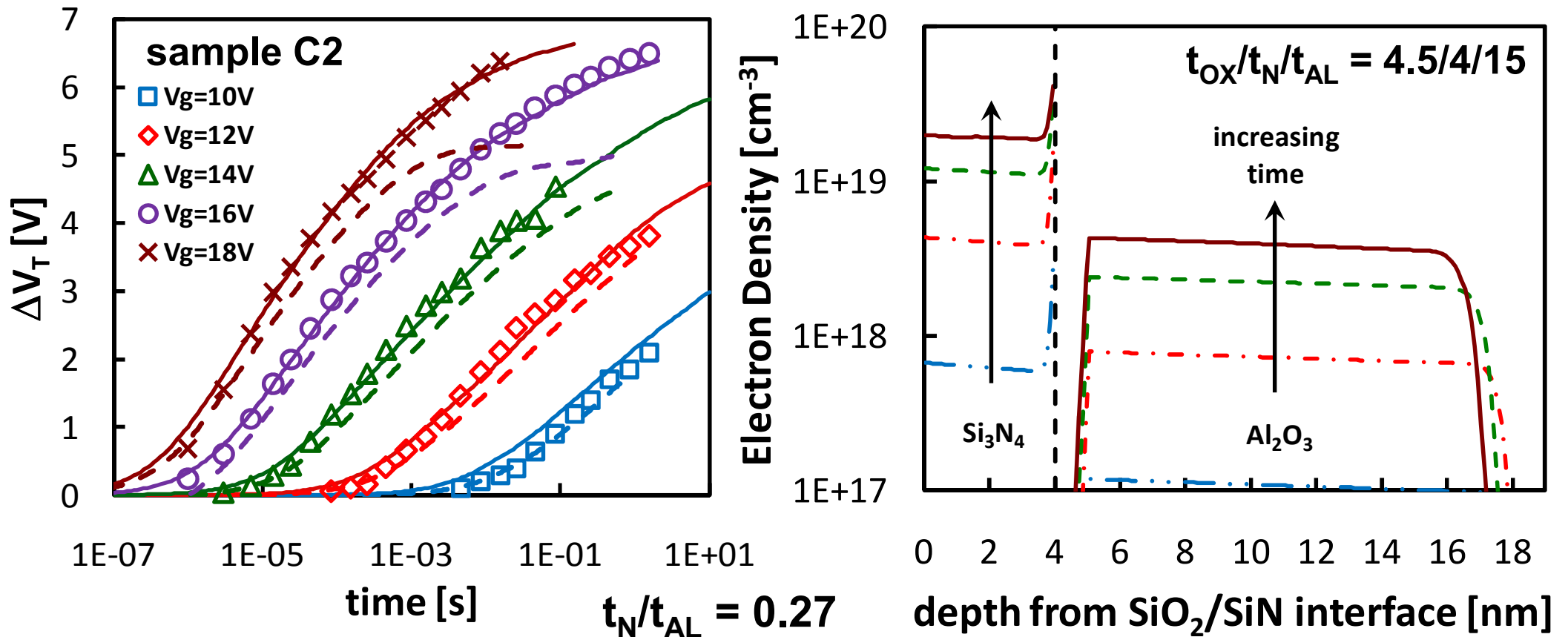
# Charge Separation

- Simulations accurately reproduce both electron and hole currents measured during charge separation experiments



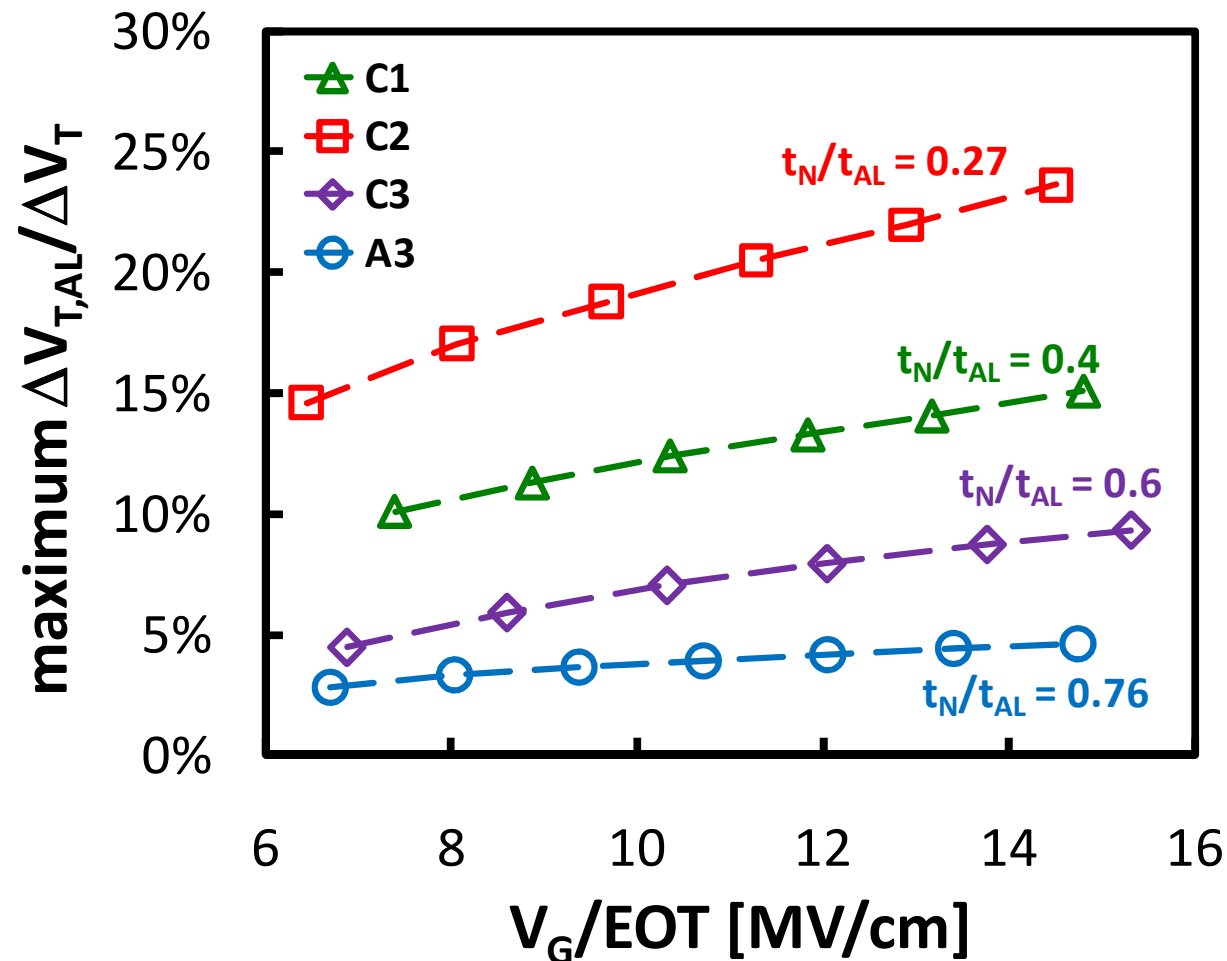
# Trapping into Alumina

- Early saturation observed in simulations when trapping in alumina is neglected on the sample having a low  $t_N/t_{AL}$  ratio
- Large amount of electron charge trapped into  $Al_2O_3$  defects



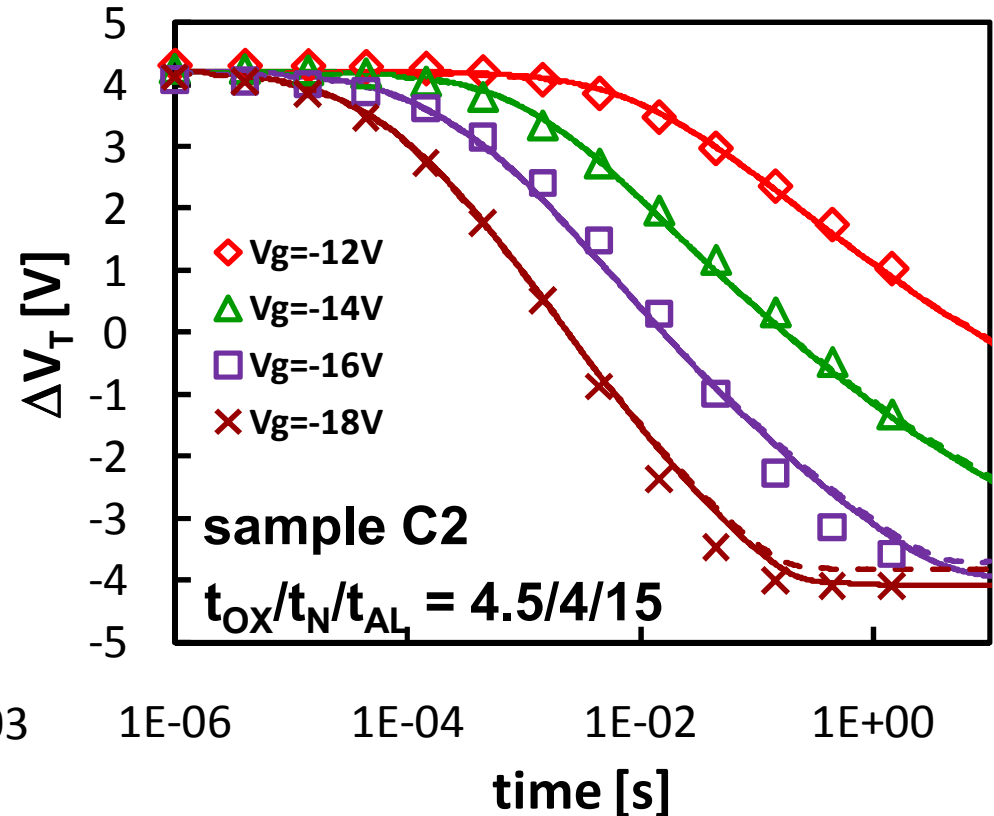
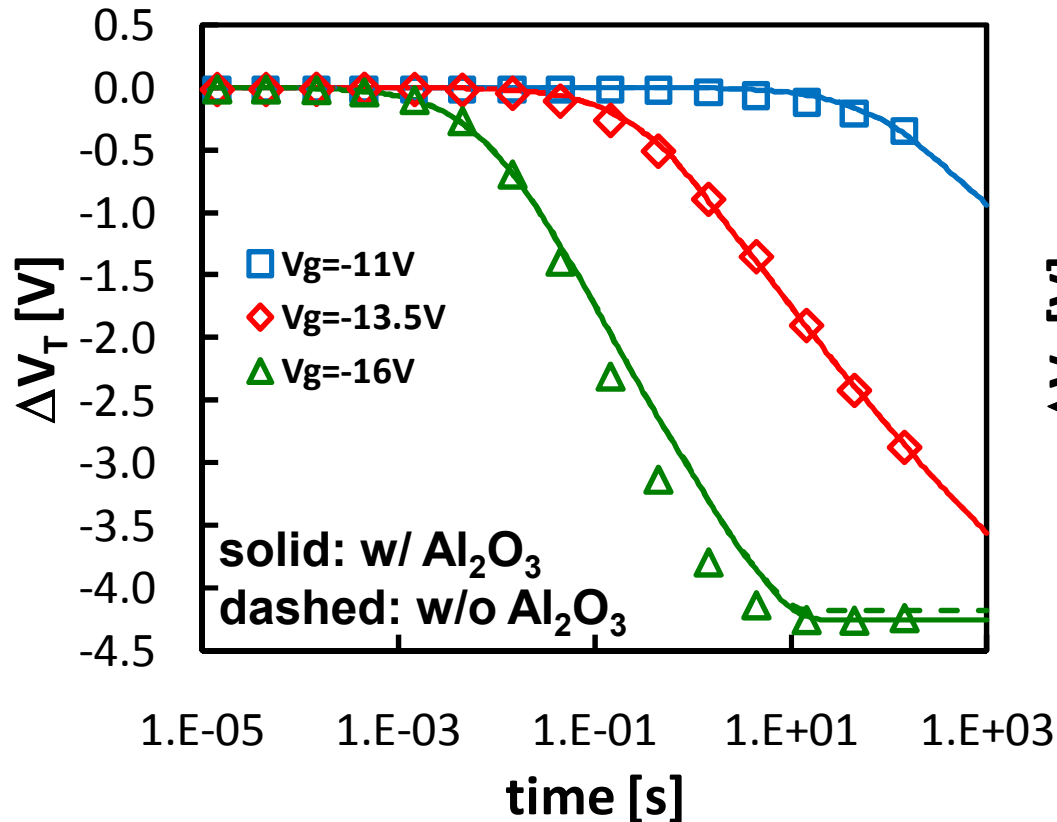
# Trapping into Alumina -2

- Electron charge trapped in the alumina layer during program can account for up to 25% of the total  $\Delta V_T$  shift
- Electron trapping in  $\text{Al}_2\text{O}_3$  is negligible for a high  $t_N/t_{AL}$  ratio



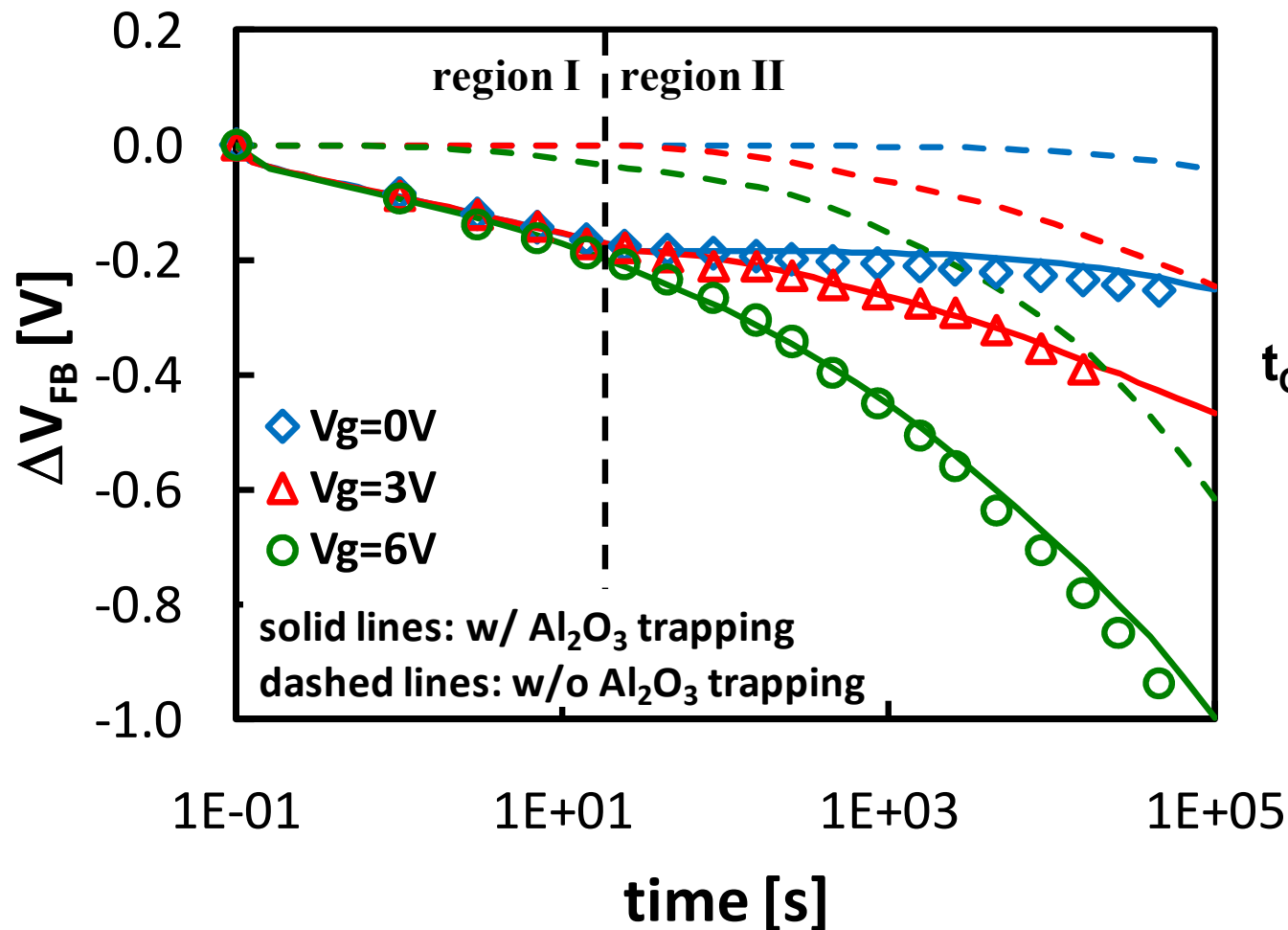
# Trapping into Alumina -3

- Hole trapping in alumina during erase is negligible
- 30% of the electron trapped into  $\text{Al}_2\text{O}_3$  during program are still there at the end of the subsequent erase operation



# Trapping into Alumina -4

- Accelerated retention tests exhibit a double slope: clear signature of charge trapping in alumina

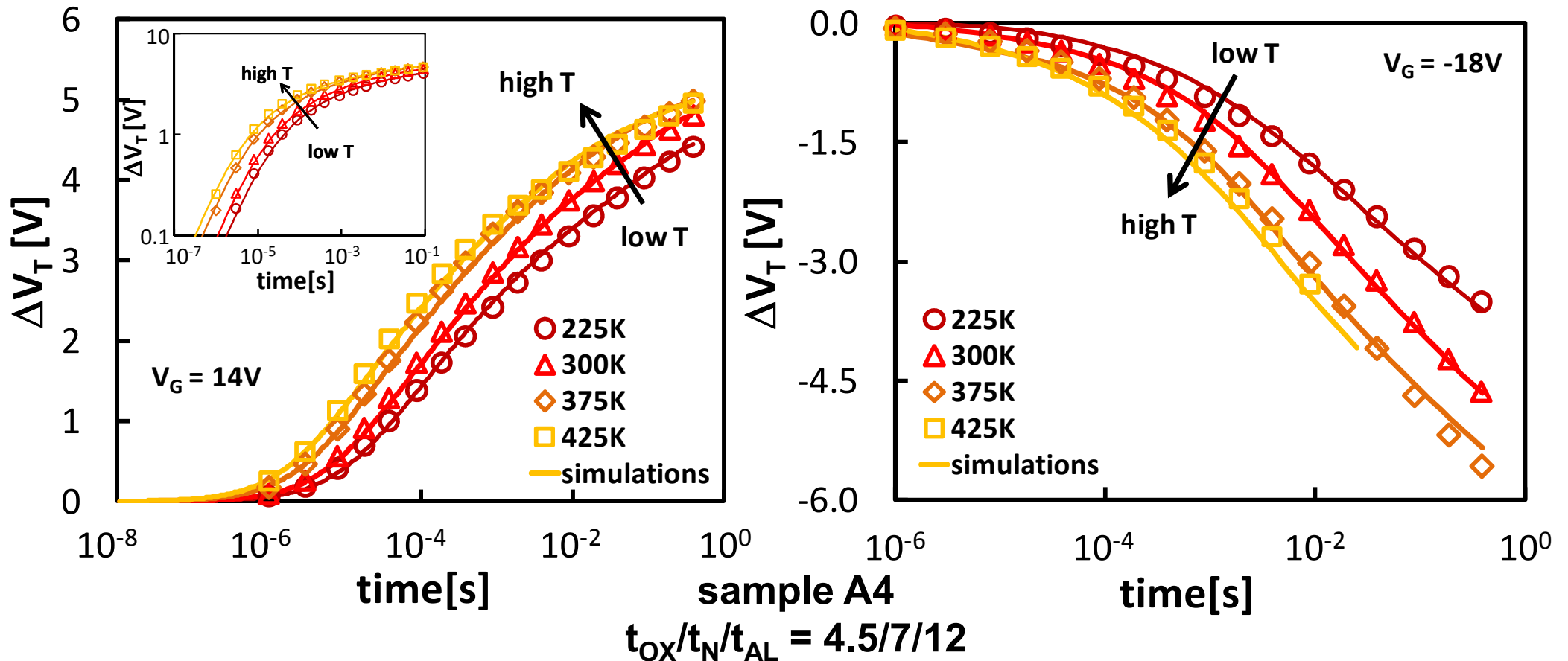


sample C1  
 $t_{OX}/t_N/t_{AL} = 4.5/6/15$



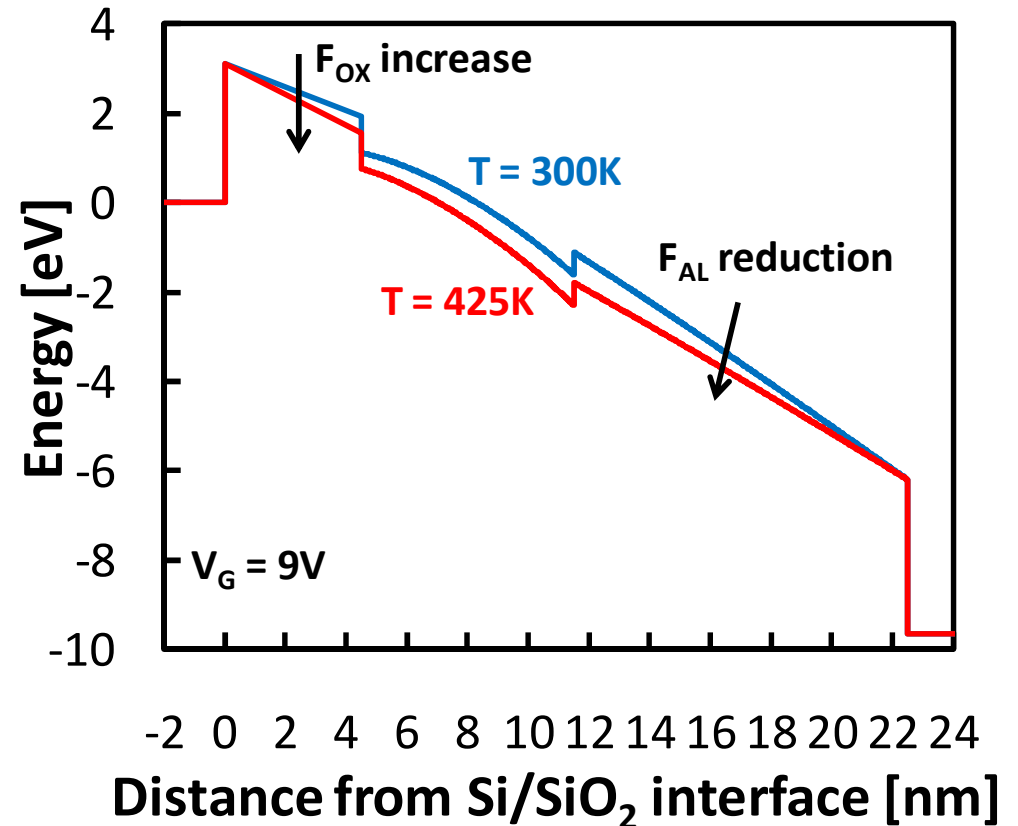
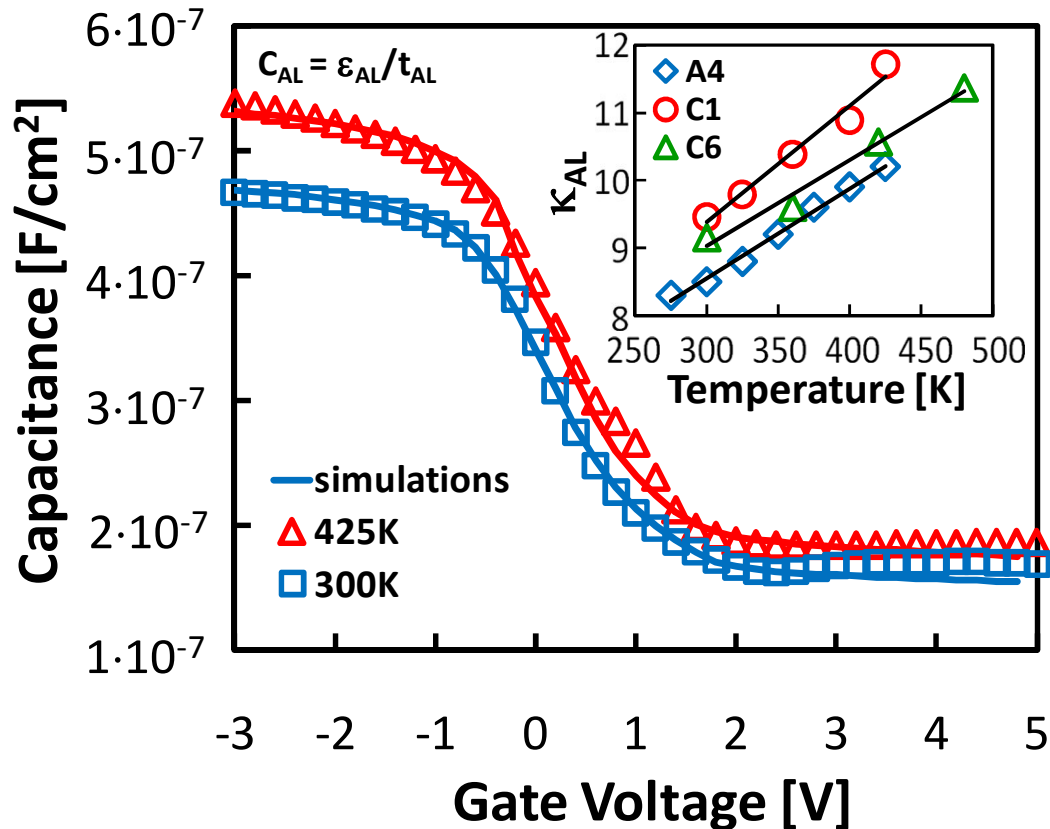
# Temperature Effects

- Program and erase operations exhibit a strong temperature dependence, which is not explained by the temperature dependence of charge trapping and emission mechanisms



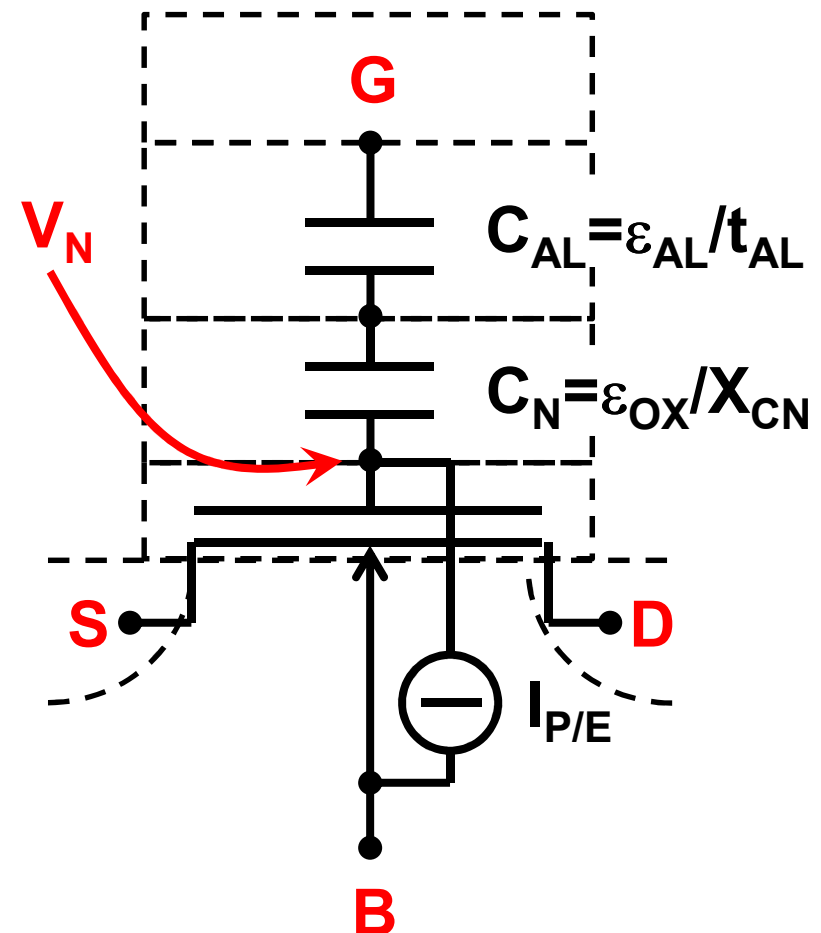
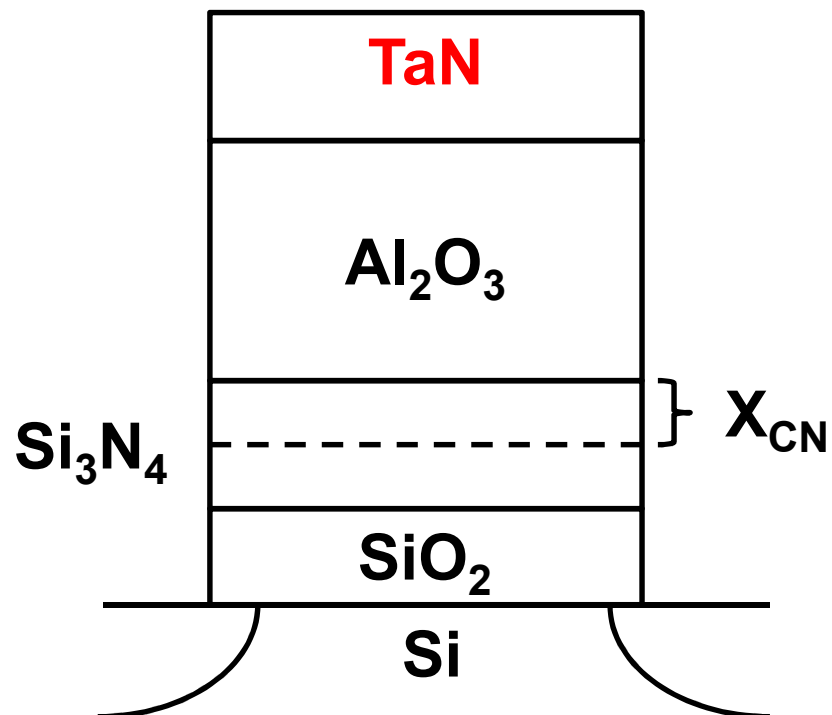
# Temperature Effects -2

- **Explanation:**  $\kappa_{AL}$  increases with temperature ( $\sim 25\%$  over 125K)
- **Voltage redistribution across the stack** ( $V_G \approx V_{OX} + V_N + V_{AL}$ ) leading to an increase of  $F_{OX}$



# Toward a Compact TANOS model

- Charge centroid findings can be used to develop simple TANOS SPICE-like models



# Conclusions

- **We developed a physical model to simulate P/E operations and reliability of TANOS devices**
- **The model exploits a new algorithm for the closed form solution of the equation system describing charge trapping and transport across the TANOS stack**
- **The model has been used to investigate the effects of temperature and charge trapping into alumina on TANOS operations and reliability**
- **This allows extracting important guidelines for stack optimizations**
- **The model allows deriving the basic approximations to develop SPICE-like compact models**